

Notice of References Cited

Application/Control No.

09/964,746

Applicant(s)/Patent Under
Reexamination
PEARSON ET AL.

Examiner

C. J. Arbes

Art Unit

3729

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U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6123248	09-2000	Tadauchi et al	
	B	US-6296722 B1	10-2001	Nishimura	
	C	US-			
	D	US-			
	E	US-			
	F	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
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	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Pb-Free External Lead Finishes for Electronic Components: Tiin-Bismuth & Tin Silver By Ron Schetty 1998 IEMT Proceedings p. 380-385
	V	Interfacial Reactions Between Lead-Free SnAgCu Solder and Ni(P) Surface Finish on Printed Circuit Boards by Zeng et al. IEE Trans on Electronics Packaging Manufacturing, Vol. 25, No.3, July 2002, p. 162-167
	W	Interactions of Lead (pb) in Lead Free Solder (Sn/Ag/Cu) System by Chung et al, 2002 Electronic Components and Technolog Conference, p. 168-175.
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.